

ABSTRACT OF THE DISCLOSURE

A method of a photolithography processing system includes illuminating a surface of a wafer supported by a table with first illumination tools and a second illumination tool by positioning the first illumination tools at varying lateral heights relative to the table to illuminate the surface of the wafer at various predetermined angles of incidence and positioning the second illumination tool to illuminate the surface of the wafer vertically from above the wafer on the table, taking pictures of the surface of the wafer with a camera while the surface of the wafer is being illuminated, receiving a signal from the camera in a controller, detecting a presence of particles on the surface of the wafer with the controller, and transporting the wafer to the process-performing or cleaning position according to whether particles are detected on the surface of the wafer.